HP LASERJET FAX

RECEIVED CENTRAL FAX CENTER

OCT 11200R

**AMENDMENT** October 11, 2006

YOR920030605US1 Serial No. 10/824,297

p.3

## AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

## **Listing of Claims:**

- 1. (previously presented) An integrated circuit (IC) comprising:
  - a plurality of devices connected together and forming circuits;
- a switchable current source selectively providing a known current to a PN junction in at least one of said plurality of devices, said switchable current source comprising:
  - a constant current source, and
  - a clamping device selectively shunting current from said constant current source; and
- a voltage measurement circuit measuring voltage across said PN junction. measured said voltage corresponding to PN junction temperature.
- 2. (canceled)
- 3. (original) An IC as in claim 1, wherein said voltage measurement circuit comprises an analog to digital converter.
- 4. (original) An IC as in claim 1, wherein said voltage measurement circuit comprises a comparator.
- 5. (original) An IC as in claim 4, wherein a reference voltage is provided to said comparator for comparison against said voltage across said PN junction.

AMENDMENT October 11, 2006

YOR920030605US1 Serial No. 10/824,297

- 6. (original) An IC as in claim 1, wherein said plurality of devices includes a plurality of field effect transistors (FETs) and said PN junction is a FET body to source/drain junction.
- 7. (original) An IC as in claim 6, wherein said IC is on a silicon on insulator chip and said plurality of FETs comprises a plurality of P-type FETs (PFETs) and a plurality of N-type FETs (NFETs) connected together in CMOS circuits.
- 8. (canceled).
- 9. (previously presented) An IC as in claim 7, wherein said voltage measurement circuit comprises an analog to digital converter.
- 10. (previously presented) An IC as in claim 7, wherein said voltage measurement circuit comprises a comparator.
- 11. (original) An IC as in claim 10, wherein a reference voltage is provided to said comparator for comparison against said voltage across said PN junction.
- 12 31 (canceled)
- 32. (previously presented) An IC as in claim 6, wherein said FET body is P-type silicon body layer in a NFET and said NFET is in a CMOS inverter.
- 33. (previously presented) An IC as in claim 32, wherein said CMOS inverter is an inverter in a ring oscillator.
- 34. (previously presented) An IC as in claim 33, wherein said ring oscillator comprises a NAND gate connected in series with a plurality of inverters, said inverter being one of

AMENDMENT October 11, 2006 YOR920030605US1 Serial No. 10/824,297

said plurality of inverters, an output of said NAND gate being in phase with an output of said inverter.

- 35. (previously presented) An IC as in claim 34, wherein said clamping FET is a NFET and an input of said NAND gate is connected to the gate of said clamping NFET, whereby a gating signal to said input selectively turns said clamping NFET off and blocks oscillation of said ring oscillator.
- 36. (previously presented) An IC as in claim 35, wherein said voltage is provided to a comparator, said comparator comparing said voltage against a reference voltage.
- 37. (currently amended) An IC as in claim 1, wherein said clamping device is [[in]] parallel with said constant current source.
- 38. (previously presented) A CMOS integrated circuit (IC) comprising:
  a plurality of field effect transistors (FETs) forming CMOS circuits;
  at least one CMOS circuit comprising:
  - a constant current source, and
- a clamping device selectively shunting current from said constant current source to a PN junction in one FET in said at least one CMOS circuit; and a voltage measurement circuit measuring voltage across said PN junction, measured said voltage corresponding to PN junction temperature.
- 39. (previously presented) A CMOS IC as in claim 38, wherein said voltage measurement circuit comprises an analog to digital converter.
- 40. (previously presented) A CMOS IC as in claim 38, wherein said voltage measurement circuit comprises a comparator and a reference voltage is provided to said comparator for comparison against said voltage across said PN junction.

AMENDMENT October 11, 2006

YOR920030605US1 Serial No. 10/824,297

- 41. (previously presented) A CMOS IC as in claim 38, wherein said PN junction is a FET body to source/drain junction.
- 42. (previously presented) A CMOS IC as in claim 41, wherein said CMOS IC is on a silicon on insulator (SOI) IC chip.
- 43. (previously presented) A CMOS IC as in claim 42, wherein said FET body is P-type silicon body layer in a NFET and said NFET is in a CMOS inverter.
- 44. (previously presented) A CMOS IC as in claim 43, wherein said CMOS inverter is an inverter in a ring oscillator.
- 45. (previously presented) A CMOS IC as in claim 44, wherein said ring oscillator comprises a NAND gate connected in series with a plurality of inverters, said inverter being one of said plurality of inverters, an output of said NAND gate being in phase with an output of said inverter.
- 46. (previously presented) A CMOS IC as in claim 45, wherein said clamping FET is a NFET in parallel with said constant current source and an input of said NAND gate is connected to the gate of said clamping NFET, whereby a gating signal to said input selectively turns said clamping NFET off and blocks oscillation of said ring oscillator.
- 47. (currently amended) A CMOS silicon on insulator (SOI) integrated circuit (IC) chip comprising:
- a plurality of field effect transistors (FETs) connected to form a plurality of CMOS circuits, said plurality of CMOS circuits including a plurality of inverters; and a ring oscillator including series connected ones of said plurality of inverters, at least one inverter of said ones comprising:
  - a constant current source, and

**AMENDMENT** October 11, 2006 YOR920030605US1 Serial No. 10/824,297

a clamping device in parallel with said constant current source selectively shunting current from said constant current source to a FET body to source/drain junction in said at least one CMOS circuit; and

a voltage measurement circuit measuring voltage across said PN junction, measured said voltage corresponding to PN junction temperature, wherein said FET body is P-type silicon body layer in a NFET and wherein said ring oscillator further comprises a NAND gate connected in series with said ones, an output of said NAND gate being in phase with an output of said at least one inverter.

## 48. (canceled)

- 49. (currently amended) A CMOS SOI IC chip as in claim 47 [[48]], wherein said clamping FET is a NFET and an input of said NAND gate is connected to the gate of said clamping NFET, whereby a gating signal to said input selectively turns said clamping. NFET off and blocks oscillation of said ring oscillator.
- 50. (previously presented) A CMOS SOI IC chip as in claim 47, wherein said voltage measurement circuit comprises an analog to digital converter.
- 51. (previously presented) A CMOS SOI IC chip as in claim 47, wherein said voltage measurement circuit comprises a comparator and a reference voltage is provided to said comparator for comparison against said voltage across said PN junction.